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A thermal management system for cooling at least one electronic component, the thermal management system including: a heat exchanger connectable to at least one electronic component, the heat exchanger configured to dissipate heat generated by the at least one electronic component; a plurality of cooling channels each connected to a respective pump and the heat exchanger, wherein: each cooling channel is configured to carry fluid between the heat exchanger and the respective pump, and each pump is configured to pump fluid along the respective cooling channel such that fluid carried by each cooling channel flows through the heat exchanger.

